

**Industry's highest
T_g 160°C**

**Compatible with the package
size of 25 mm square or more**

Pot life is long 3 days

**Applications
IC Package/Automotive**

Mount reinforcement of semiconductor packages and electronic parts for automotive camera modules, millimeter-wave radar modules, ECU.

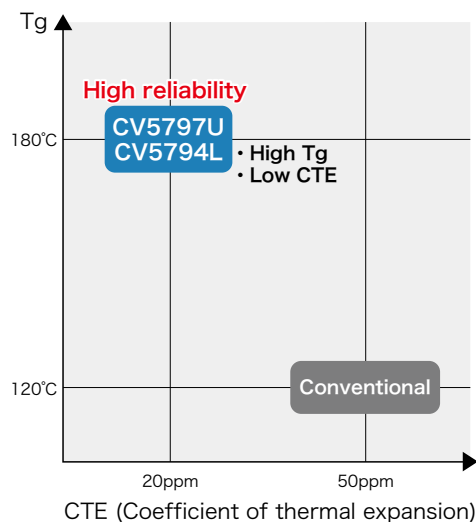
LEXCM^{DF}

CV5797 series CV5794 series

High heat resistance secondary mounting sidefill/underfill materials

Achieves automotive grade assembly-level reliability requirements with the industry's highest heat resistance and low CTE. Package periphery (edge and corner) reinforcement materials available. RoHS compliant.

Concept



Reinforcement type (Applicable IC package)

Sidefill

For large-size package
(e.g. 25 mm square or more)

BGA
Motherboard

For QFN package

QFN
Motherboard

Underfill

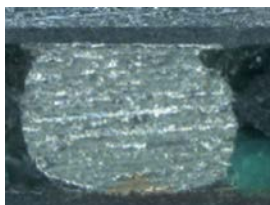
For small and medium size package
(e.g. 20 mm square or less)

BGA
Motherboard

Correspond to temperature cycle test under automotive environment

CV5797U/ CV5794L

Conventional



Item	CV5797U	Conventional
Temperature cycling test (TCT) -55°C⇔125°C 30min	6000 cycles Pass	3000 cycles Pass

General properties

Item	Unit	CV5797 series Sidefill (Corner glue)	CV5794 series Underfill
Glass transition temp. (T _g)	°C	160	160
C.T.E.1	ppm/°C	14	21
Elastic modulus (25°C)	GPa	18	15
Storage condition	—	-20°C/ 6months	

Please see our website for Notes before you use.

The above data are typical values and not guaranteed values.

industrial.panasonic.com/ww/electronic-materials

Panasonic Industry Co., Ltd. Electronic Materials Business Division

Panasonic Industry CV5797

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